The Stackup Legend below this is static.
If you change the stackup, update the Legend.

Layer Stack Up Detail for: Ref_Design.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-4
Bottom Layer	(.GBL)	1.4mil	
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
3450MIL X 4950MIL

Number of Layers : 2
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 8 MIL
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

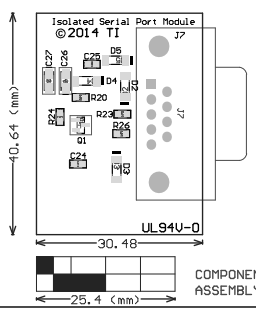
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: [No Variations]

ALL MATERIAL REQUIRED FROM TOP SIDE	BOARD #: XX####	REV: 1.0	SUN REV: Not Used Control
LAYER NAME = Top Assembly Drawing			
PLOT NAME = Top Assembly Drawing	GENERATED 8 :: 8/22/2014	17:49:29	TEXAS INSTRUMENTS

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TEXAS INSTRUMENTS

PROJECT TITLE: Isolated Serial Board
DESIGNED FOR: Public Release
FILE NAME: IsolatedSerial.PcbDoc
ENGINEER: Mars Leung
LAYOUT BY: Mars Leung
SCALE: 0.70
ALTIUM DESIGNER VERSION: 10.0.0.27009

The Stackup Legend below this is static.
If you change the stackup, update the Legend.

Layer Stack Up Detail for: Ref_Design.PcbDoc

Layer Name	Number Documents	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	
Bottom Layer	(.GBL)	1.4mil	FR-4
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DESIGN INFORMATION

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3450MIL X 4950MIL

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MIN. VIA PAD SIZE: 24 MIL
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PER IPC-D-275 CLASS 2 LEVEL C
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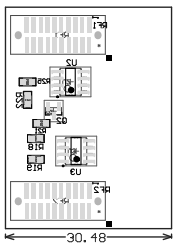
MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: Isolated Serial Board
DESIGNED FOR: Public Release
FILE NAME: IsolatedSerial.PcbDoc

ENGINEER:	LAYOUT BY:
Mars Leung	Mars Leung
SCALE: 0.70	ALTIUM DESIGNER VERSION: 10.0.0.27009

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